

# QUICKCIRCUITS

...understanding the importance of precision

## PCB Manufacturer & Assembler

In the same facility,  
under the same roof,  
by the same company.

## PCB Manufacturing Capabilities

### A.O.I.

Full Automatic Optical  
Inspection to Gerber Data

### FORMATS ACCEPTED:

All Gerber formats

ODB++

HPGL

DXF

DPF

Emma

EDIF 4.0.0

### MATERIAL TYPES:

FR4, Polyimide, PTFE, High Tg, High Frequency

Max. Circuit Size (Con.PTH)

Max. Circuit Size (M/L)

Max. Board Thickness

Min. Board Thickness (Conv.PTH)

Max. Layer Count

Min. Board Thickness (M/L)

(Min. Multilayer thickness on request)

Min. Track Width

Min. Gap Width

### DRILLING

Min. Finished Hole Size

Max. Aspect Ratio

Min. Annular Ring

### RESIST MASK

Liquid Photoimageable

Min. solder dam

### NOTATION

Standard White/Yellow (Min. line width)

Other colours on request

Photoimageable standard

### ELECTRONIC DATA PROCESSING

Ucamco Ucam & Graphiccode GC-CAM front end software  
(6 stations)

Direct data transfer active 24 hours a day

### DRILLING FORMATS

Any ASCII format

### HIGH SPECIFICATION

upon request

upon request

5.0

0.2

36

4L 0.4

0.1

0.13

### HIGH SPECIFICATION

0.15

10.0:1

0.127

### HIGH SPECIFICATION

0.1

### HIGH SPECIFICATION

0.127

### STANDARD SPECIFICATION

550x550

457x355

4.0

0.5

14

0.6

0.15

0.15

### STANDARD SPECIFICATION

0.3

8.0:1

0.127

### STANDARD SPECIFICATION

0.127

### STANDARD SPECIFICATION

0.127

## SURFACE

H.A.S.L. (Pb & Pb free)  
Electroless Nickel/  
Immersion Gold  
Silver  
Immersion Tin  
Electrolytic Hard Gold  
over Nickel  
Pure Gold (Wirebonding)  
Carbon Ink  
Peelable Solder Resist

## HIGH SPECIFICATION

0.030 - 0.100  $\mu\text{m}$  gold  
over 3-6  $\mu\text{m}$  nickel  
  
1 -5  $\mu\text{m}$  gold  
over 3 - 5  $\mu\text{m}$  nickel

## STANDARD SPECIFICATION

0.030 - 0.100  $\mu\text{m}$  gold  
over 3-6  $\mu\text{m}$  nickel  
  
1 -5  $\mu\text{m}$  gold  
over 3 - 5  $\mu\text{m}$  nickel

## BARE BOARD TESTING

Flying Probe Testing (3 machines)  
Min. pad size  
Min. pitch  
Testing to Gerber data  
Single Board Testing

## HIGH SPECIFICATION

0.05  
0.1

## STANDARD SPECIFICATION

0.1  
0.2

## IMPEDENCE TESTING

Using Time Domain Reflectometry

$\pm 5\%$

$\pm 10\%$

## TECHNOLOGIES

Impedance Control  
Blind/Buried Vias  
Hole Plugging  
High Aspect Ratio Plating  
HDI  
Sequential Build up Technology  
Epoxy Resin Plugging



Quick Circuits Ltd. 1 Loverock Road,  
Reading, Berkshire, RG30 1DZ, UK

Tel: +44 (0)118 950 8921 Fax: +44 (0)118 956 8327  
sales@quick-circuits.com www.quick-circuits.com